ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® international and H	IPC, Bannock	burn, Illinois. A	Il rights reserved untions.	under both	This docum level parts,	ent is a declara the declaration	tion of the s encompass	ubstances es all lowe	within the manufac r level materials for	turer listed which the	item. Note: manufactur	if the item is an as er has engineering	sembly with lower responsibility.	
				Form Type Distribute					erials and I	ials and Mfg Information				
Supplier Information														
Company name* Compan			apany unique ID			Unique ID Authority				Respo	Response Date*			
onsemi										2025-0	2025-06-07			
Contact Name Title - Conta			tact			Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewards Product Env			nviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative			esentative			Phone - Representative*			Email	Email - Representative*				
Product-Env-Stewards Product Envi			viro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Da	e Version		Manufacturing Site		Weight*	UOM	Unit Type	
	SS35		3A 50V SCHOTTKY RECTI			2025-06-07 PANJITFG		PANJITFG	232.5		mg	Each		
Manufacturing Proccess Inform	ation													
Terminal Plating / Grid Array Material Terminal Base		Alloy	J-STD-020 MSI	L Rating	Peak Pro	cess Body 7	Temperatu	re Max Time at Pe	ak Temper	ature Nun	nber of Reflow Cy	cles		
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	seco	onds 3				
Comments														
level 1 - maximum time at peak tempera	ture during so	ldering is 10-3	0 seconds											
For more information regarding materi	al composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.798	mg	Supplier	Silicon (Si)	7440-21-3		3.7707	mg
			В	Nickel (Ni)	7440-02-0		0.0057	mg
			Supplier	Gold (Au)	7440-57-5		0.0209	mg
			В	Arsenic (As)	7440-38-2		0.0008	mg
Die Attach Solder	4.36	mg	Supplier	Silver (Ag)	7440-22-4		0.109	mg
			А	Lead (Pb)	7439-92-1	7a	4.033	mg
			Supplier	Tin (Sn)	7440-31-5		0.218	mg
Lead Frame	90.9231	mg	Supplier	Iron (Fe)	7439-89-6		0.1091	mg
			Supplier	Copper (Cu)	7440-50-8		90.7867	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0273	mg
Mold Compound-Black	132.0	mg		Metal Hydroxide	proprietary data		4.62	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		10.56	mg
			Supplier	Carbon Black (C)	1333-86-4		0.66	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		105.6	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		10.56	mg
Plating	1.4189	mg	Supplier	Tin (Sn)	7440-31-5		1.4189	mg